

PCB Manufacturing Notes

General Info

Board dimensions – 40mm x 70mm
Number of layers – 2
Smallest hole – 0.3mm
Number of holes – Approx 180
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
Layer 01 (Top)	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

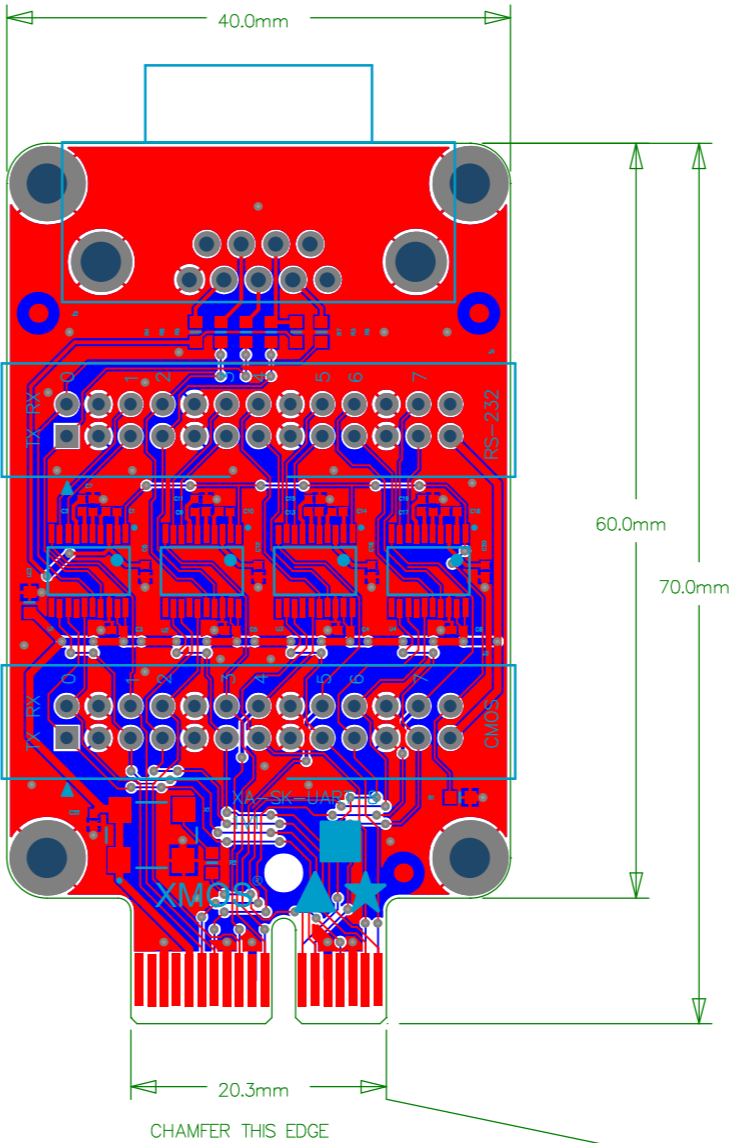
The supplier may not add copper thieving/balancing.

Finish

- A.) Conductive finish
Plating to be immersion gold.
- B.) Soldermask
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.
- C.) Silkscreen
Colour white. Supplier should remove any silkscreen which overhangs pads.

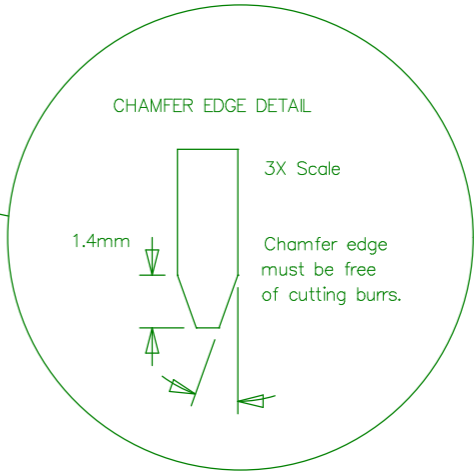
Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.
Hole size is finished size.



XMOS LTD = XPCB-056 = 1V1 = 2 AUGUST 2012

LAYER – FABRICATION INSTRUCTIONS
PCB COPPER LAYER 1 (TOP) SILKSCREEN TOP
PCB COPPER LAYER 2 (BOTTOM)



XMOS®

Project Name
XPCB-056 (XA-SK-UART8)

Sheet	Date	Revision
A4	2 AUGUST 2012	1V1

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Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

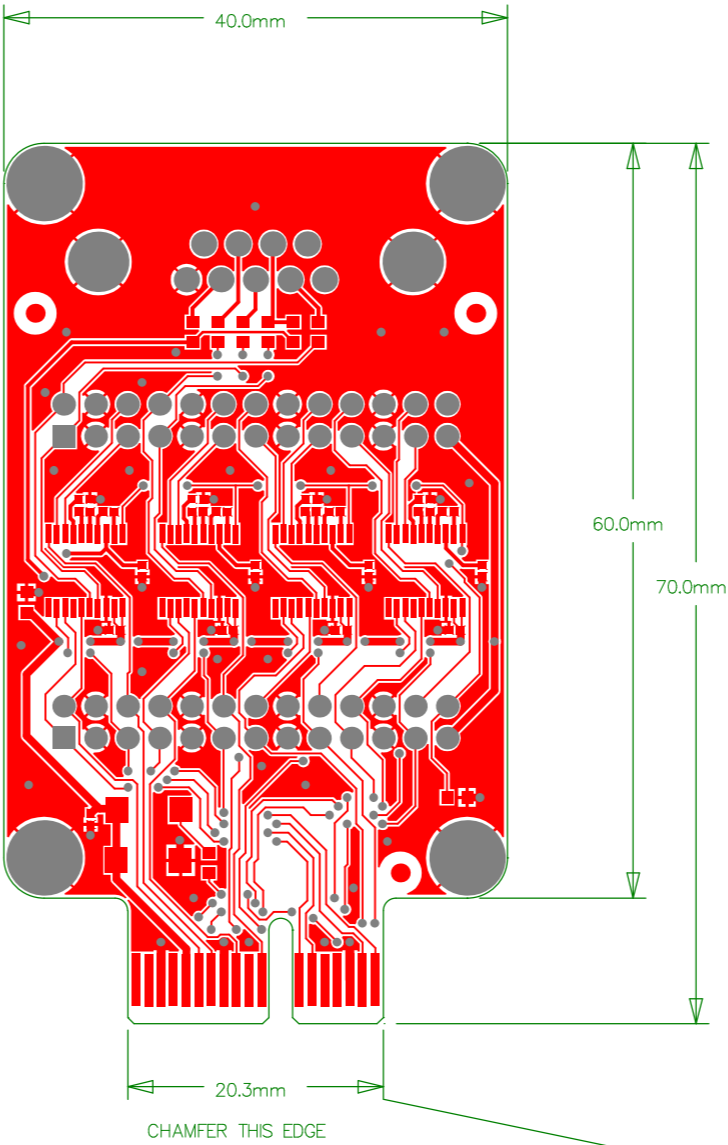
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

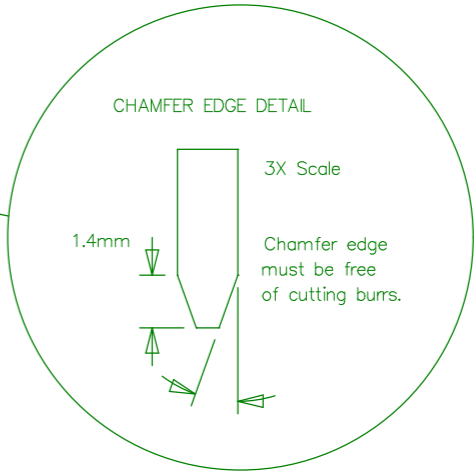
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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FABRICATION INSTRUCTIONS
PCB COPPER LAYER 1 (TOP)



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Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

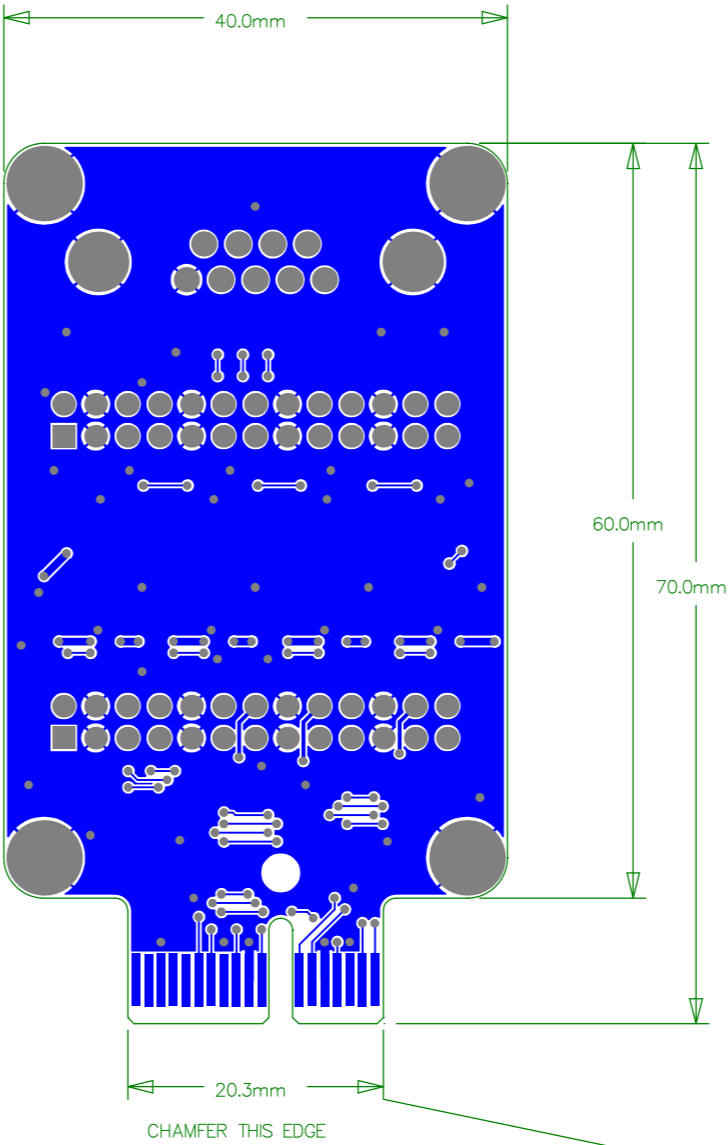
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

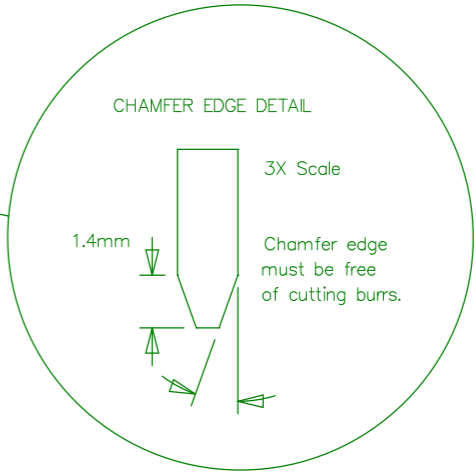
Drill Data

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FABRICATION INSTRUCTIONS

PCB COPPER LAYER 2 (BOTTOM)



Project Name
XPCB-056 (XA-SK-UART8)

Sheet	Date	Revision
A4	2 AUGUST 2012	1V1

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PCB Manufacturing Notes

General Info

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Number of layers – 2
Smallest hole – 0.3mm
Number of holes – Approx 180
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

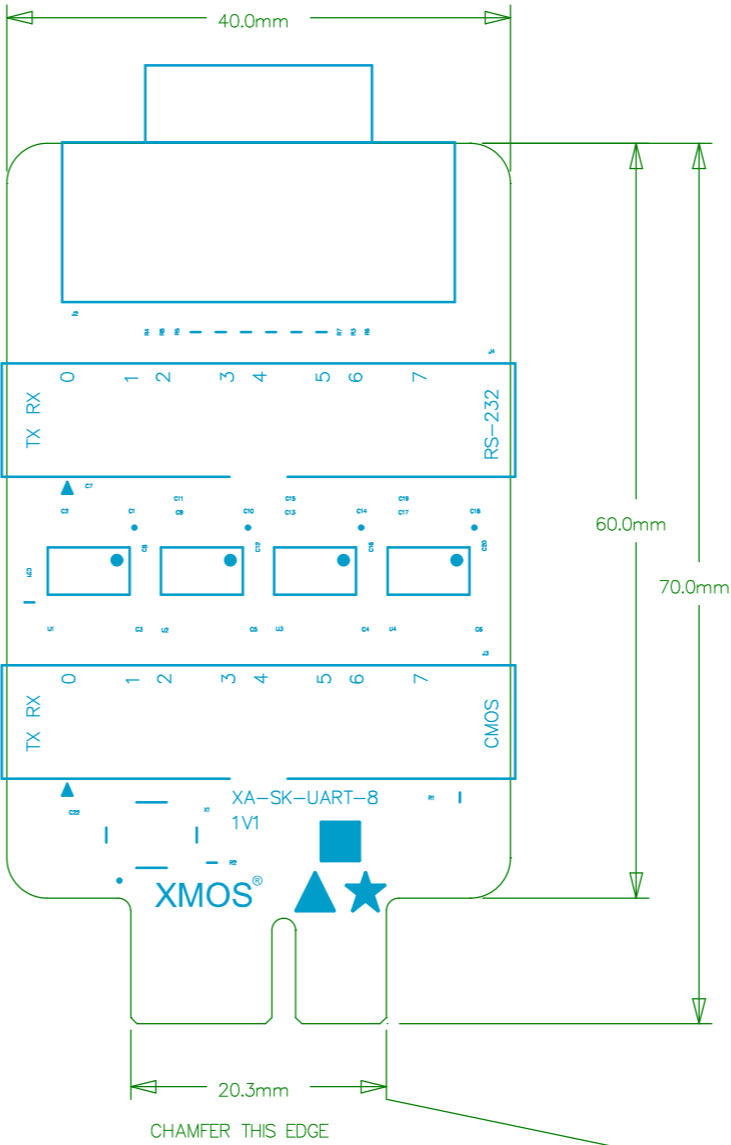
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

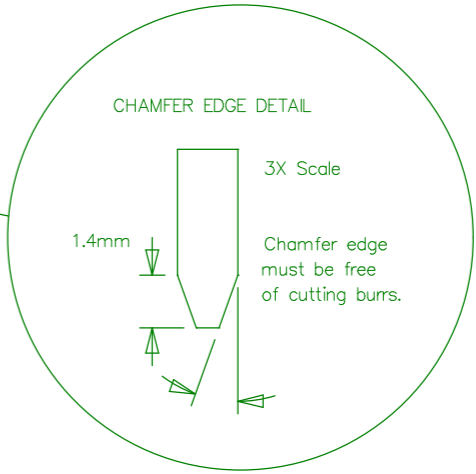
Drill Data

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FABRICATION INSTRUCTIONS

SILKSCREEN TOP



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Number of holes – Approx 180
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

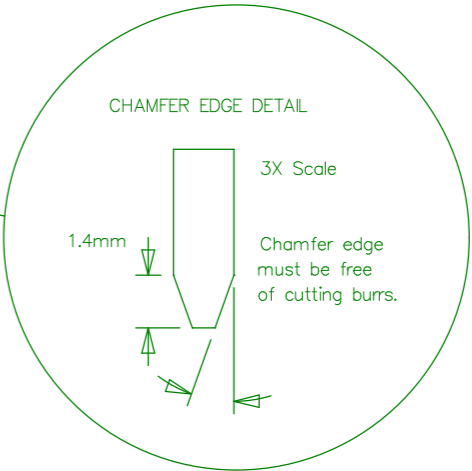
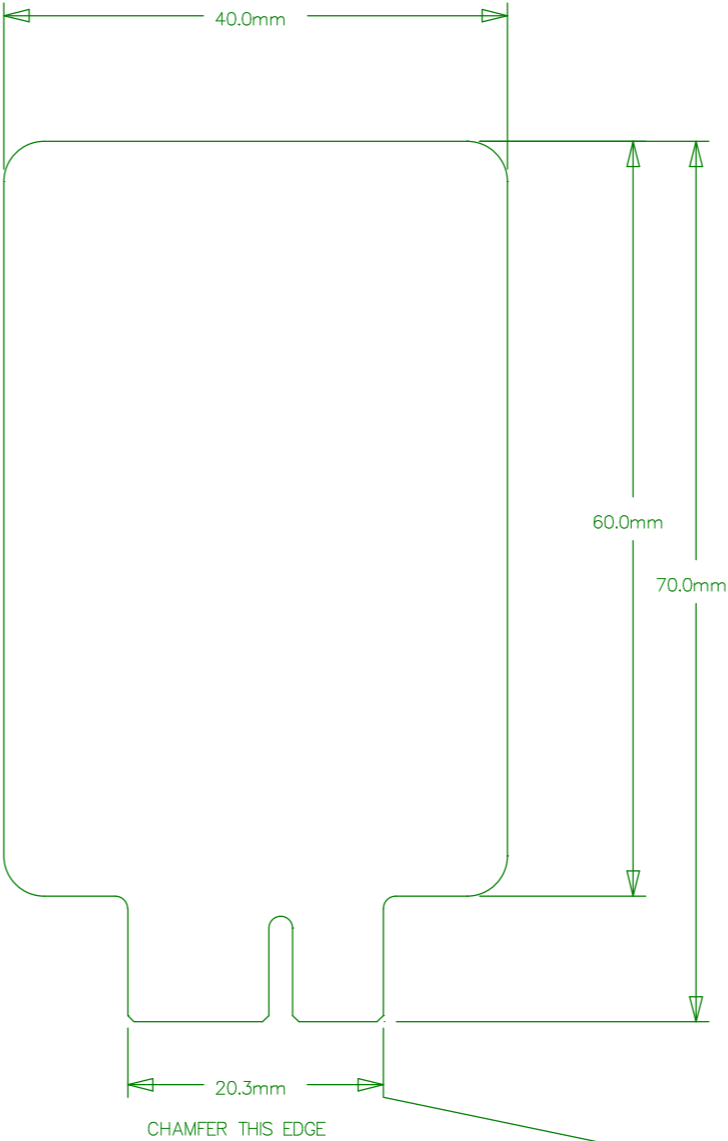
- A.) Conductive finish
Plating to be immersion gold.
- B.) Soldermask
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.
- C.) Silkscreen
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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FABRICATION INSTRUCTIONS

SLKSCREEN BOTTOM



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	0.5oz
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Not required.

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Finish

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Plating to be immersion gold.

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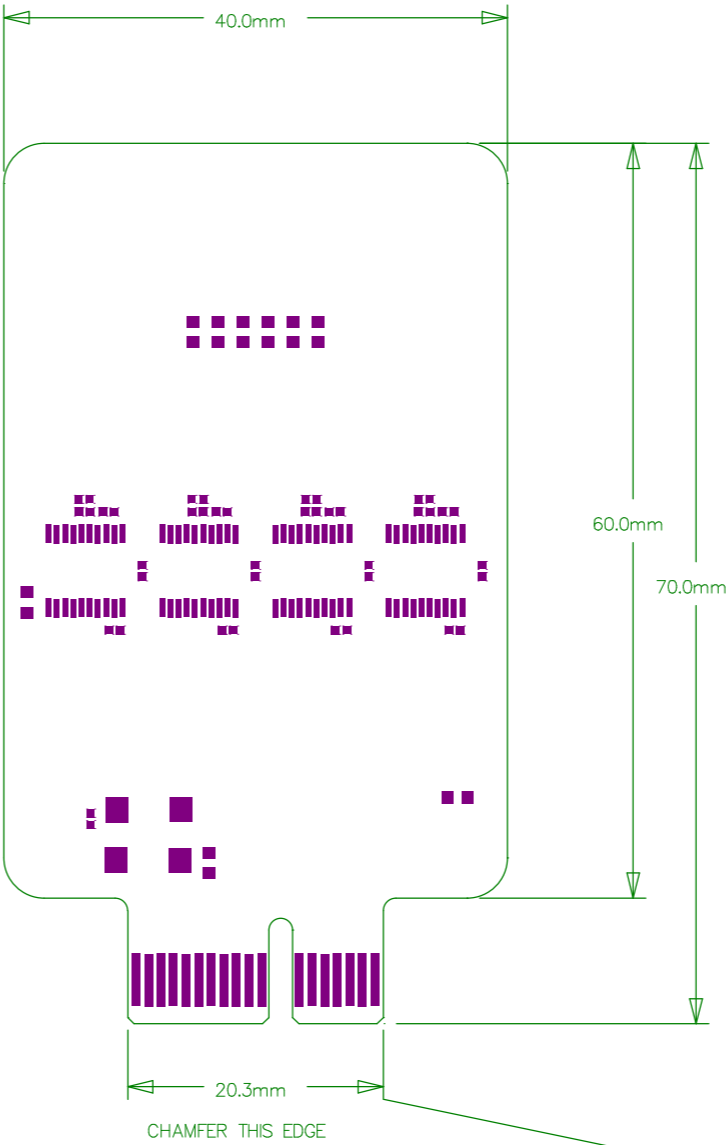
C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

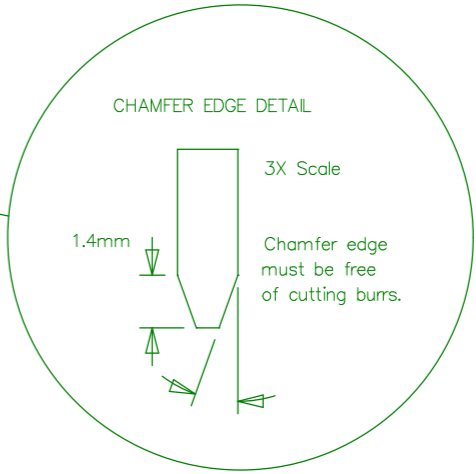
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FABRICATION INSTRUCTIONS



PASTE MASK TOP



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Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

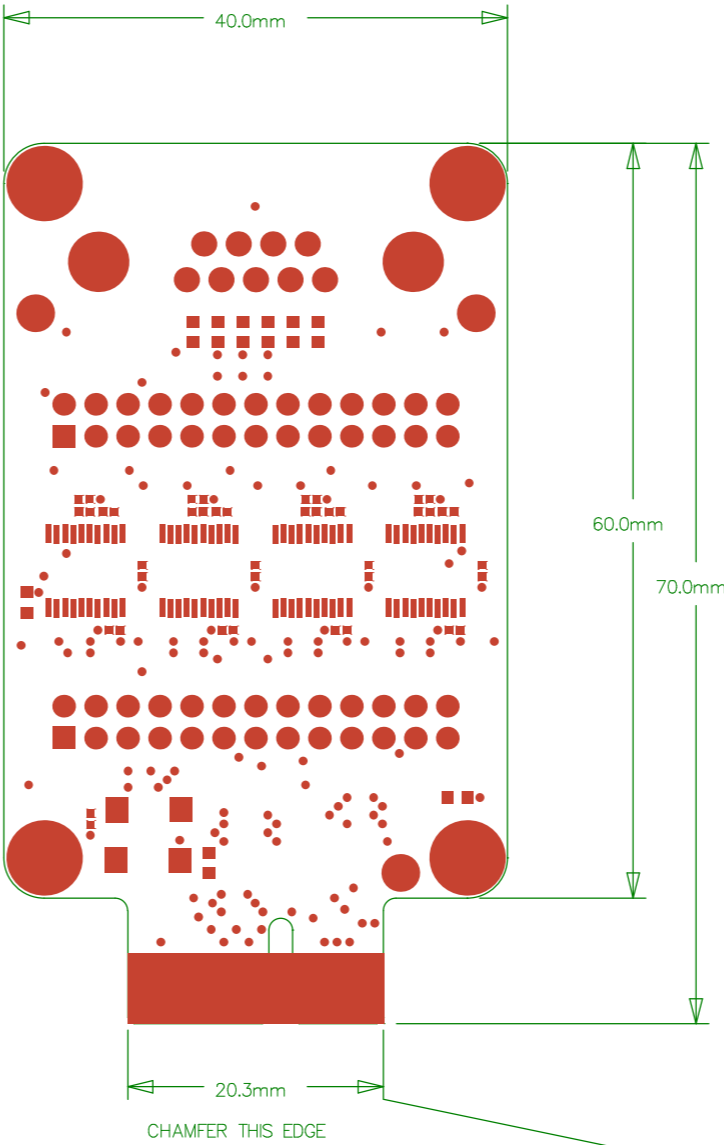
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FABRICATION INSTRUCTIONS

SOLDER MASK TOP



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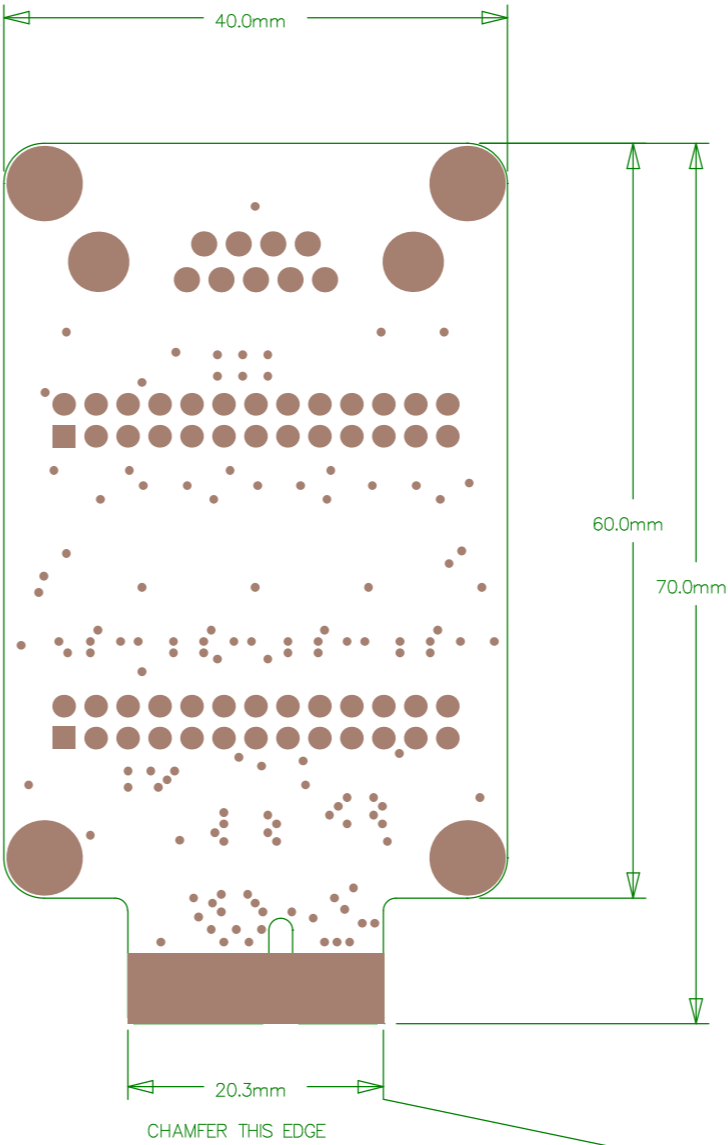
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FABRICATION INSTRUCTIONS

SOLDER MASK BOTTOM



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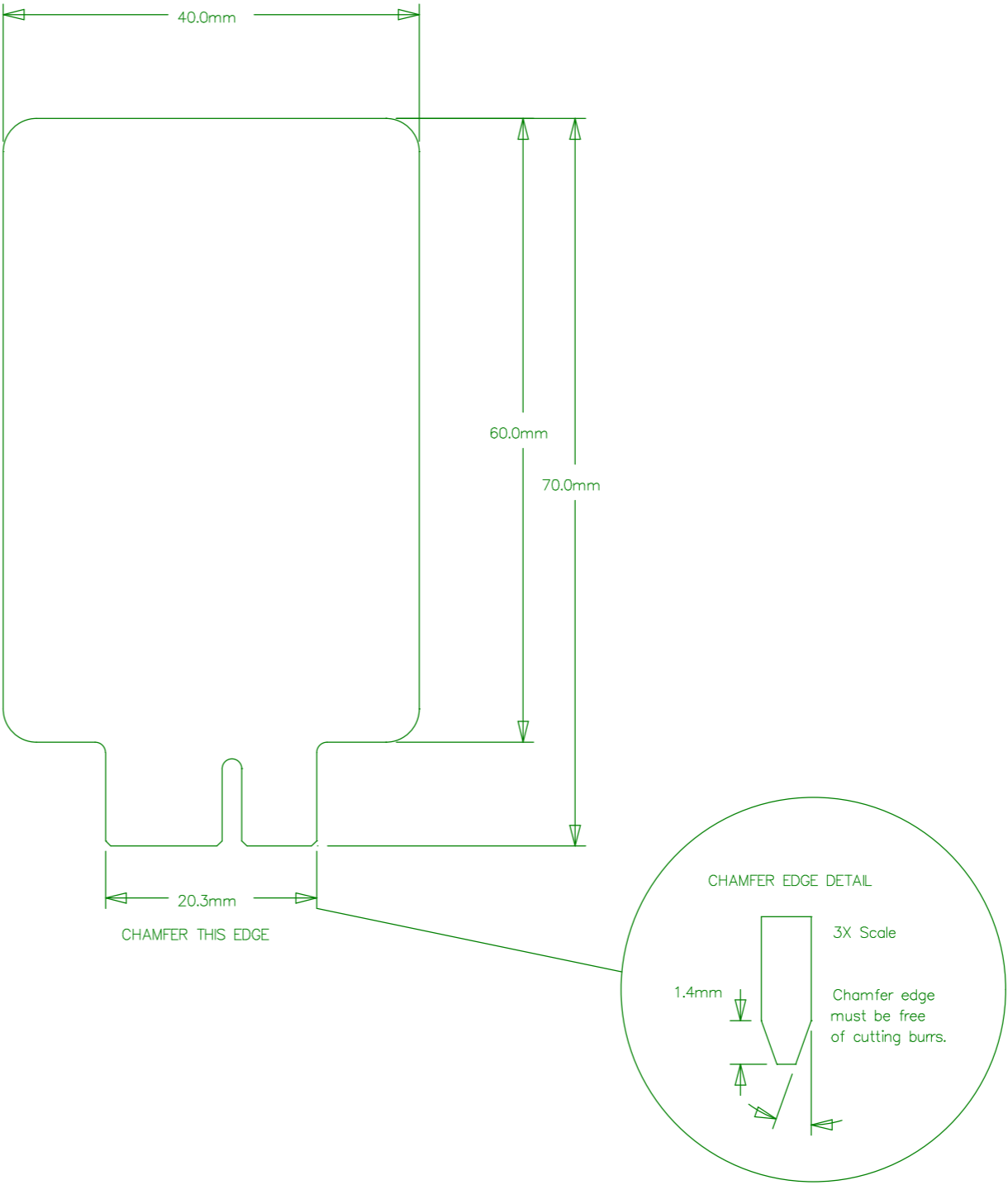
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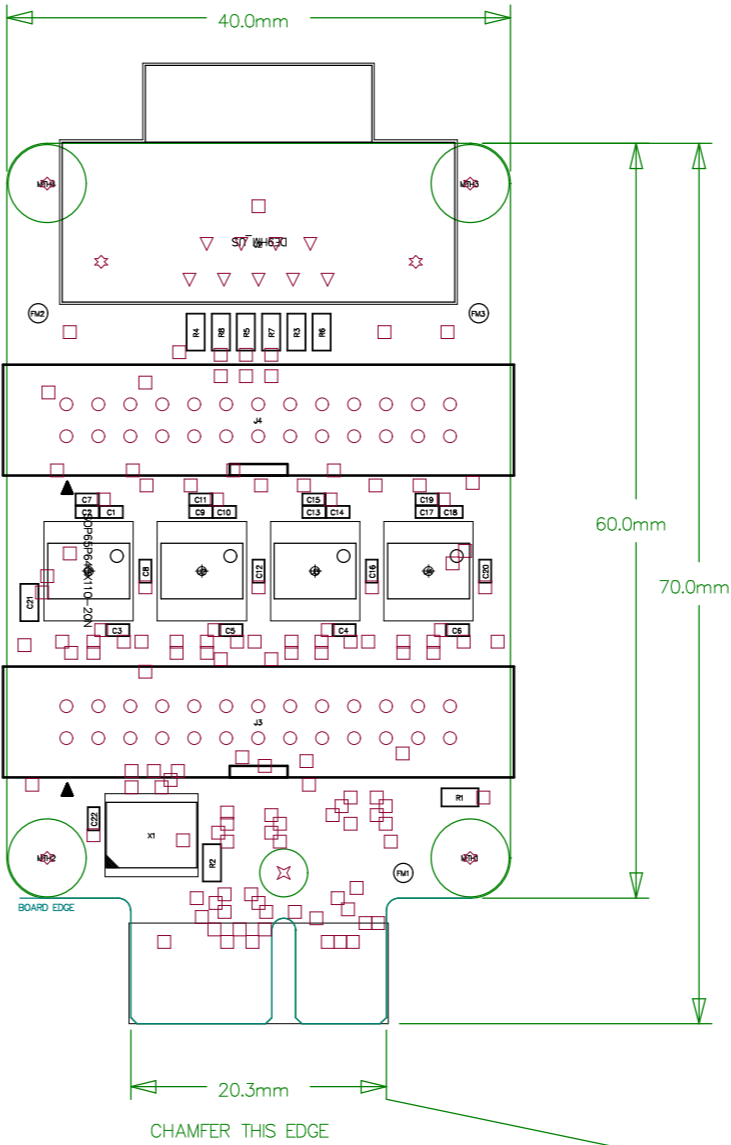
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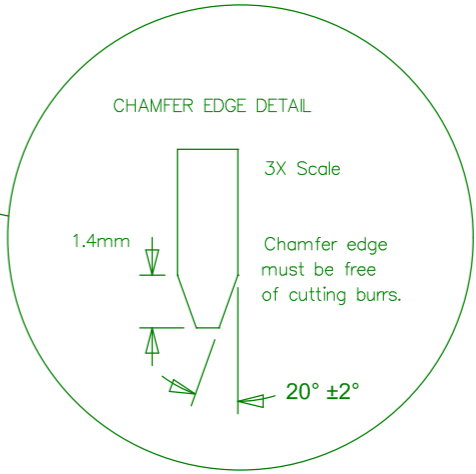
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FABRICATION INSTRUCTIONS

DRILL DRAWING

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	125	0.3mm (11.811mil)	PTH	Round
○	52	1mm (39.37mil)	PTH	Round
▽	9	1.2mm (47.244mil)	PTH	Round
☆	1	2.8mm (110.236mil)	NPTH	Round
☆	6	3.2mm (125.984mil)	PTH	Round
	193 Total			

Drill Drawing.

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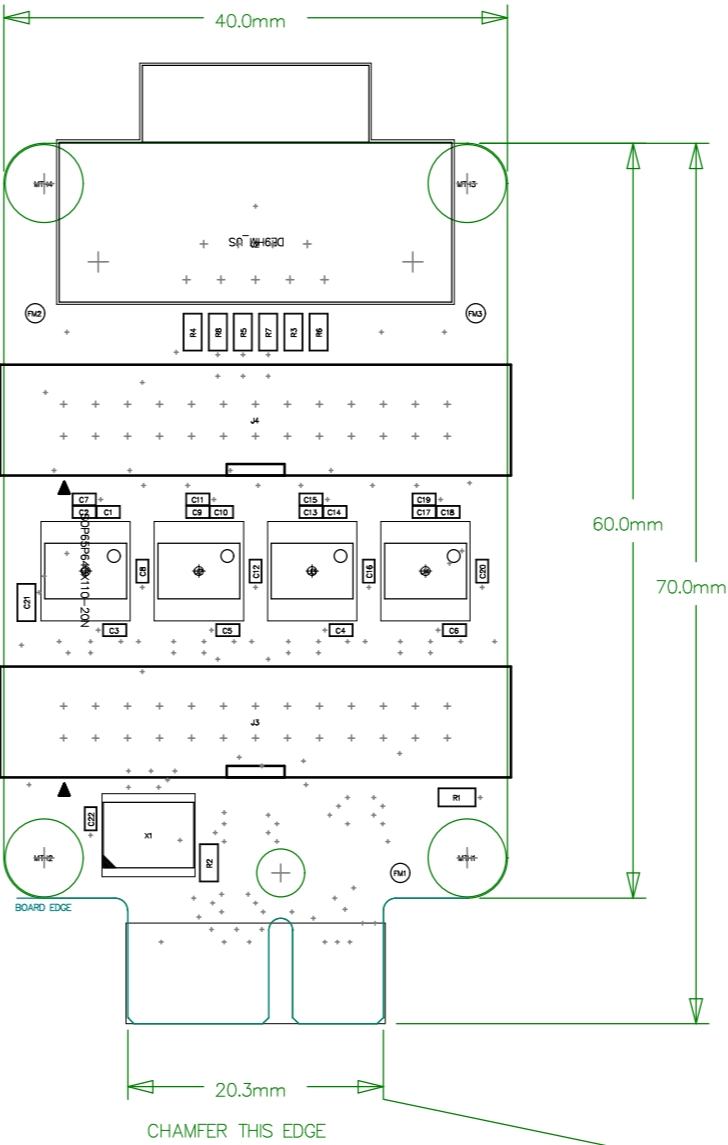
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BOM

Multi UART Slice

Source Data From:

Project:

Variant:

XA-SK-UART-8.SchDoc

XPCB-056_XA-SK-UART-8.PrjPCB

None



Report Date:

07/12/2012

13:10:31

Print Date:

07-Dec-12

1:10:35 PM

#	LibRef	Designator	Description	Quantity
1	E-01-0002	R1	RES 10k 0603 1%	1
2	E-01-0008	R2	RES 33R 0603 1%	1
3	E-01-0010	R3, R4	RES 330R 0603 1%	2
4	E-01-0012	R5, R6	RES 0R 0603 1%	2
5	E-02-0002	C1, C2, C3, C4, C5, C6, C7, C8, C9, C10, C11, C12, C13, C14, C15, C16, C17, C18, C19, C20, C22	MLCC 100nF 0402 X7R 16V	21
6	E-02-0005	C21	MLCC 4.7uF 0603 X5R 6.3V	1
7	E-04-0071	J2	D-Subminiature Connector, 9 pin, Male, Right Angle, US Footprint, with screw locks	1
8	E-04-0073	J3, J4	Male Header, Unshrouded, 26 Way, 2x13, 0.1" Pitch	2
9	E-07-0032	X1	Crystal Oscillator, 3.3V, 1.8432MHz, 7x5mm SMD, Overall Stab. ±50ppm	1
10	E-13-0102	U1, U2, U3, U4	RS232 2 Tx/2 Rx, With Charge Pump, ESD Protected, 250kbps, 3V-5.5V, TSSOP20	4
11	P-01-0011	PROD1, PROD2, PROD3, PROD4	Feet, Nylon, M3, 6mm Standoff	4
Approved			Notes	40